

**HEAT SINK COMPOUND
ISOL SL 06**

ISOL 6, Heat Sink Compound is a non-curing, water resistant paste heavily filled with heat conductive metallic oxides in a Silicone base. It is used for maintaining a positive heat-sink seal that improves heat transfer from the electrical / electronic component / device to the heat sink or chassis, there by increasing the overall efficiency of the component / device.

PRODUCT FEATURES:

- Capable of high thermal conductivity
- Bleed resistant, non-drying, non-melt and non-curing in nature.
- Heat – resistant up 200⁰C.

TECHNICAL SPECIFICATIONS

Colour & Appearance:	Milky White paste
Bleed, percent after 24 hrs @ 200 ⁰ C:	< 0.1
Evaporation, percent after 24 hrs @ 200 ⁰ C:	< 5
Specific Gravity @25 ⁰ C:	2.3
Thermal Conductivity, k factor, cal / cm ² / °c / sec. / cm :	0.0010
Electric Strength at 50mils:	450
Arc Resistance, Seconds:	120
Dielectric Constant	
@ 100 Hz:	4.9
@ 1000 Hz:	4.9
Dissipation Factor	
@ 100 Hz:	0.0050
@ 1000 Hz:	0.0010
Volume Resistivity (Ohms-cm):	2.0 x 10 ¹⁵

APPLICATIONS

Generally used as a thermal coupling of electrical / electronic devices to heat sinks such as base or mounting studs of transistors, diodes and rectifiers.
Also used as a non-flammable coating for fly back transformer connections in TV chassis and similar applications.

PACKING AND SHELF LIFE

ISOL 6, Heat Sink Compound is available in 1 Kg Packs. The recommended usage period is 12 months from the date of manufacture.

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